## Quarterly Reliability Monitoring Results

### Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier | User Part Number | | | | | |
|---|---|---|---|---|---|---|
| Nexperia B.V. | BZX84-B68 | | | | | |
| **Name of Laboratory** | **Part Description** | | | | | |
| | Nexperia DHAM | Zener | | | | |
| Assembly reliability labs | SMD package | | | | | |
| **Test** | | **Test Conditions** | **Duration** | **# Lots** | **# Quantity** | **# Rejects** |
| # 1 | **TEST**<br>Pre- and Post-Stress Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below |
| # 2 | **PC**<br>Preconditioning | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering | 24 hours<br>168 hours<br>3 cycles | 1514 | 64430 | 0 |
| # 5 | **HTRB**<br>High Temperature Reverse Bias | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, VR = 80 % of rated reverse voltage | 1000 hours | 250 | 11400 | 0 |
| # 5c | **SSOP**<br>Steady State Operational | MIL-STD-750-1<br>M1038 Method B<br>Tj = Tjmax, Iz = 100% of max. datasheet reverse current | 1000 hours | 44 | 1920 | 0 |
| # 7 | **TC**<br>Temperature Cycling | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C | 500 cycles | 311 | 14080 | 0 |
| # 8 **or** | **UHAST**<br>Unbiased HAST | JESD22-A118<br>Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | 0 |
| # 8a | **AC**<br>Autoclave | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia) | | | | |
| # 9 | **H3TRB**<br>High Humidity High Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage[1] | 1000 hours | 311 | 14080 | 0 |
| # 10 | **IOL**<br>Intermittent Operating Life | MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure ΔTj = 100 °C | 333 hours | 312 | 14120 | 0 |
| # 20 | **RSH**<br>Resistance to Solder Heat | JESD22-A111<br>260 °C ± 5 °C | 10 s | 269 | 8070 | 0 |
| # 21 | **SD**<br>Solderability | J-STD-002 | | 222 | 6660 | 0 |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

### Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|---|---|---|---|---|---|
| Nexperia DHAM | Zener | 11400 | 0 | 0,37 | 2,68E+09 |

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